

IN THE SPECIFICATION

Please replace the paragraph beginning on page 1, line 4 with the following:

The present application is a division of Application Serial No. 09/525,514, filed on March 6, 2002, entitled SEMICONDUCTOR DEVICE AND METHOD FOR PRODUCING THE SAME BY DICING, which is based upon and claims the benefit of Japanese Patent Application No. 11-76566 filed on March 19, 1999, and No. 11-196345 filed on July 9, 1999, the contents of which are incorporated herein by reference.

IN THE CLAIMS

Please cancel claims 1 – 20.

Please add the following new claims:

21. (New) A semiconductor device comprising:

a semiconductor chip provided by cutting a semiconductor wafer by dicing;

a bump disposed on a surface of the semiconductor chip;

a protective member disposed on the surface of the semiconductor chip, the protective member having an opening portion from which the bump is exposed, the protective member being for protecting the semiconductor chip when the semiconductor wafer is cut by dicing; and

a movable portion disposed on a region that is covered by the protective member.

22. (New) The semiconductor device according to claim 21, wherein the movable portion has a movable electrode detecting change of a capacity.

23. (New) The semiconductor device according to claim 21, wherein the movable portion provides a capacity detection type acceleration sensor.

24. (New) The semiconductor device according to claim 21, wherein the movable portion faces the protective member.

25. (New) The semiconductor device according to claim 24, wherein the protective member is formed to provide a space for preventing contact with the movable portion.

26. (New) The semiconductor device according to claim 25, wherein the protective member has a recess corresponding to the movable portion.

27. (New) The semiconductor device according to claim 24, wherein the movable portion is disposed in an opening portion formed on the semiconductor chip.

28. (New) The semiconductor device according to claim 27, wherein the opening portion includes a back surface processed portion and an adhesive film disposed on the semiconductor chip so as to cover an opening defined by the back surface processed portion.

29. (New) The semiconductor device according to claim 21, wherein the movable portion is disposed in the semiconductor chip close to the surface where the protective member is disposed.

30. (New) The semiconductor device according to claim 21, further comprising a second bump, wherein both bumps are arranged on both sides of the surface of the semiconductor chip with respect to the movable portion.

31. (New) A semiconductor device comprising:

Q2 a semiconductor chip having first and second plane surfaces and diced outer surfaces, the semiconductor chip defining an opening portion that opens to the first plane surface, the semiconductor chip having a movable portion disposed in the opening portion;

a pad portion formed on the first plane surface; and

a protective member disposed on the first surface so as to cover the opening portion and to expose the pad portion.

32. (New) The semiconductor device according to claim 31, further comprising a bump on the pad portion.

33. (New) The semiconductor device according to claim 31, wherein the movable portion provides a capacity detection type acceleration sensor.

34. (New) The semiconductor device according to claim 31, wherein the protective member is formed to provide a space for preventing contact with the movable portion.

35. (New) The semiconductor device according to claim 31, wherein the protective member has a cap portion.

36. (New) The semiconductor device according to claim 31, wherein the protective member has a recess corresponding to the movable portion.

37. (New) The semiconductor device according to claim 31, wherein the opening portion includes a back surface processed portion that opens to the second plane surface of the semiconductor chip, and further comprising an adhesive film disposed on the second plane surface of the semiconductor chip so as to cover an opening defined by the back surface processed portion.

38. (New) The semiconductor device according to claim 31, wherein the movable portion is disposed in the semiconductor chip close to the first plane surface.